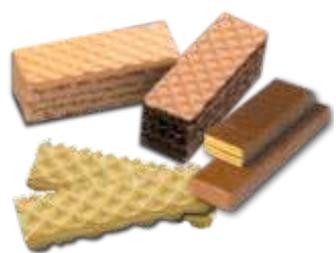




An ISO 9001:2008 Company

## Wafer Cutting Machines "WC" Series



**WC with special Guarding**

High capacity ✦ Less space ✦ Quality cuts ✦ Easy cleaning

## Automatic Wafer Cutting Machine (WC)

R&D Engineers manufactures a series of cutting machines, WC machine can handle different sizes of wafer sheets (230 mm x 290 mm, .....). These are fully automatic machines for cutting flat and Hollow wafers filled with cream. In the cutting operation the wafer book are first pushed through one set of cutters and then at a right angle (perpendicular) through a second set of cutters. Fixed and tensioned cutting wires in removable frames are used. Changeover to other cutting sizes is facilitated by quickly and easily changing the cutting frames and pushers. These machines are designed for high-capacity plants. They occupy less space.

### Operation Of The WC Machine

A number of wafer blocks having together a height of about 70 mm are put between pressing piece and cutting frame of the first table and lightly pressed to the pressing piece as well as to the striking point. It is necessary that the block lie at the striking point if both sides of the block are to be cut evenly. If after the first cut, it shows that the two waste strips are not equally wide; this can be corrected by adjusting the striking point. During practical operations it has shown that the width of the waste strip should be about 5mm, which is absolutely necessary if the entire block is to be cut cleanly.

Now it must be decided whether one wishes to work with non-automatic or automatic operation. The difference between these two possibilities consists in the fact that, in case of non-automatic operation, the button must be pushed for each individual cutting procedure. Whilst in case of automatic operation the second sliding carriage switches on the first sliding carriage to new movement as soon as it returns to the initial position.

### Features Of WC Series: (Special Edition)

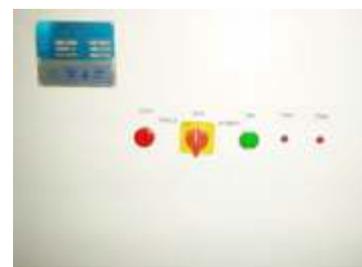
- ✦ Rigid and strong machine frame ensures smooth operation.
- ✦ All four sides of the wafer are trimmed during the cutting operation which gets collected in the collecting tray.
- ✦ All parts of the machine in contact with the product are fabricated from stainless steel.
- ✦ Extensive safety features have been built in the machine for the protection of personnel.
- ✦ Control panel is complete with all required control units and operator control buttons.

### Technical Data:

Machine Variables	WC1	WC2
Size of the plate (in mm)(approx.)	230 x 290	270 x 370
Stack height ( in mm)	10 to 70	10 to 70
Minimum cutting width (in mm)	16	16
Cutting Wire (Spring Steel)(in mm)	0.5	0.5
Connected Load (in kw)	1.5	1.5
Dimensions (in mm)		
Length	1700	1700
Width	940	940
Height	1150	1150
Net Weight (in kgs) (approx)	650	650
Shipping Volume (CBM)	2	2

\* Modifications Reserved

We are constantly guided by our principle of offering our customers better and better machines; to give increased efficiency and higher levels of automation. The technical data and illustrations are subject to change without notice



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